

Dual N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)max}\left(\Omega\right)$	I _D (A)	Q _g (Typ.)		
20	0.300 at V _{GS} = 4.5 V	0.6			
	0.350 at V _{GS} = 2.5 V	0.4	0.75		
	0.420 at V _{GS} = 1.8 V	0.2	0.75		
	0.500 at V _{GS} = 1.5 V	0.05			

FEATURES

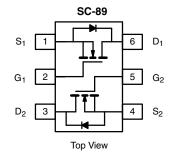
- TrenchFET® Power MOSFET
- 100 % R_g Tested



RoHS

APPLICATIONS

- Load/Power Switching for Portable Devices
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits



ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V_{DS}	20	V	
Gate-Source Voltage		V_{GS}	± 12		
Continuous Drain Current /T = 150 °C\a	T _A = 25 °C	I.	0.60 ^{a, b}		
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C	- I _D	0.49 ^{a, b}	Α	
Pulsed Drain Current		I _{DM}	2		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	0.18 ^{a, b}	Α	
Marrian Davis Disaination	T _A = 25 °C	P _D	0.22 ^{a, b}	W	
Maximum Power Dissipation ^a	T _A = 70 °C	' Б	0.14 ^{a, b}	VV	
Operating Junction and Storage Temperature Range	je	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Тур.	Max.	Unit
Maximum Junction-to-Ambient ^b	t ≤ 5 s	R _{thJA}	470	565	°C/W
iviaximum junction-to-ambient	Steady State	' 'thJA	560	675	J/VV

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 5 s.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					I.		
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		17		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 1.8			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.4		1	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$ $V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 30 ± 1		
Zawa Cata Vallana Duain Commant		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.3 \text{ V}$ $V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V, T _J = 85 °C			3		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	2			Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 0.5 \text{ A}$		0.300		1	
Drain-Source On-State Resistance ^a	D	$V_{GS} = 2.5 \text{ V}, I_D = 0.2 \text{ A}$		0.350		Ω	
Dialii-Source Oil-State nesistance	R _{DS(on)}	$V_{GS} = 1.8 \text{ V}, I_D = 0.2 \text{ A}$		0.420			
		$V_{GS} = 1.5 \text{ V}, I_D = 0.05 \text{ A}$		0.500			
Forward Transconductance	9 _{fs}	$V_{DS} = 10 \text{ V}, I_{D} = 0.5 \text{ A}$		7.5		S	
Dynamic ^b							
Input Capacitance	C _{iss}			43		pF	
Output Capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		14			
Reverse Transfer Capacitance	C _{rss}			8			
Total Gate Charge	Qq	$V_{DS} = 10 \text{ V}, V_{GS} = 8 \text{ V}, I_{D} = 0.6 \text{ A}$		1.3	2	nC	
<u>-</u>	ŭ			0.75	1.2		
Gate-Source Charge	Q_{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 0.6 \text{ A}$		0.15			
Gate-Drain Charge	Q_gd			0.13			
Gate Resistance	R_g	f = 1 MHz	2.4	12.2	24.4	Ω	
Turn-On Delay Time	t _{d(on)}			11	20		
Rise Time t _r		$V_{DD} = 10 \text{ V}, R_L = 20 \Omega$		16	24	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 0.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		26	39		
Fall Time	t _f			11	20		
Drain-Source Body Diode Characterist	ics						
Pulse Diode Forward Current ^a	I _{SM}				2	Α	
Body Diode Voltage	V_{SD}	I _S = 0.5 A		8.0	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			10	15	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	Q_{rr} $I_F = 0.5 \text{ A, dl/dt} = 100 \text{ A/}\mu\text{s}$		2	4	nC	
Reverse Recovery Fall Time	t _a	i _F = 0.5 A, αί/αι = 100 A/μS		5		ns	
Reverse Recovery Rise Time	t _b			5			

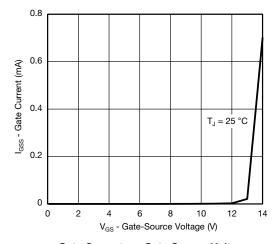
2

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

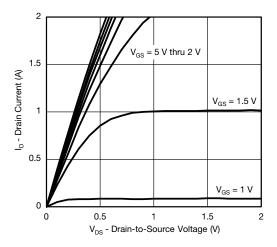
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.



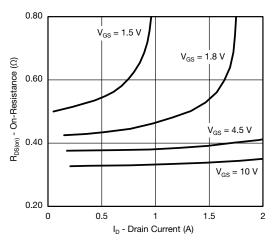
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



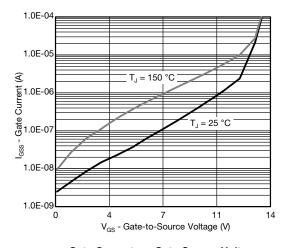
Gate Current vs. Gate-Source Voltage



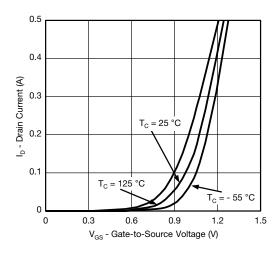
Output Characteristics



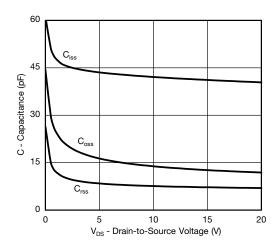
On-Resistance vs. Drain Current



Gate Current vs. Gate-Source Voltage



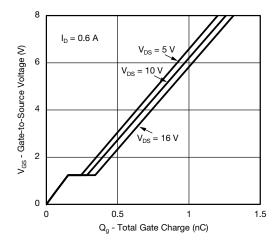
Transfer Characteristics



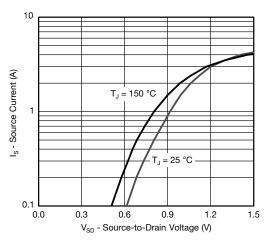
Capacitance



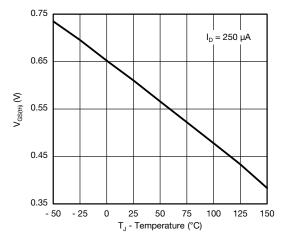
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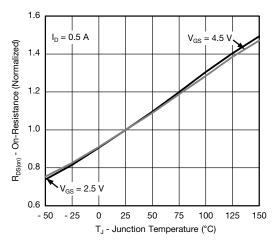
Gate Charge



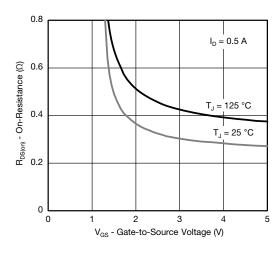
Soure-Drain Diode Forward Voltage



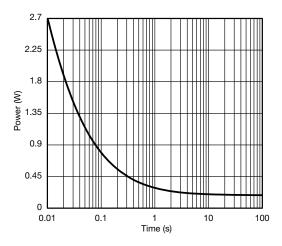
Threshold Voltage



On-Resistance vs. Junction Temperature



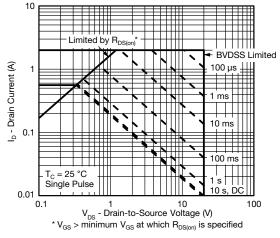
On-Resistance vs. Gate-to-Source Voltage



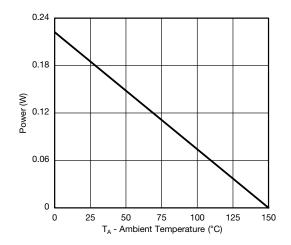
Single Pulse Power, Junction-to-Ambient



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

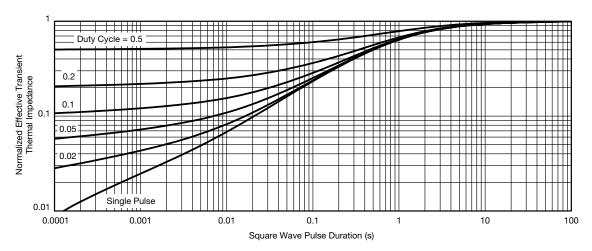






Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

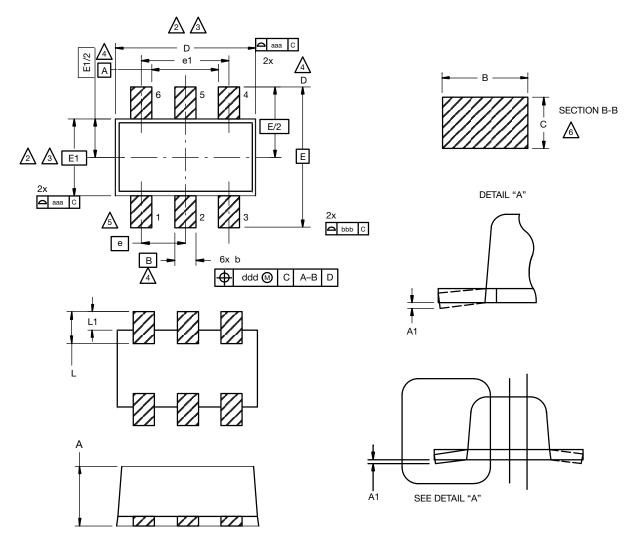


Normalized Thermal Transient Impedance, Junction-to-Ambient

服务热线:400-655-8788 5



SC-89 6-Leads (SOT-563F)



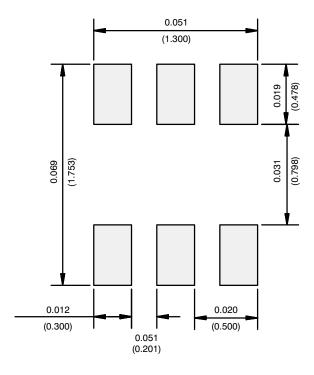
Notes

- 1. Dimensions in millimeters.
- Dimension D does not include mold flash, protrusions or gate burrs. Mold flush, protrusions or gate burrs shall not exceed 0.15 mm per dimension E1 does not include interlead flash or protrusion, interlead flash or protrusion shall not exceed 0.15 mm per side.
- 3. Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, the bar burrs, gate burrs and interlead flash, but including any mismatch between the top and the bottom of the plastic body.
- 4. Datums A, B and D to be determined 0.10 mm from the lead tip.
- 5. Terminal numbers are shown for reference only.
- 6. These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIM.	MILLIMETERS					
	MIN.	NOM.	MAX.			
Α	0.56	0.58	0.60			
A1	0	0.02	0.10			
b	0.15	0.22	0.30			
С	0.10	0.14	0.18			
D	1.50	1.60	1.70			
E	1.50	1.60	1.70			
E1	1.15	1.20	1.25			
е	0.45	0.50	0.55			
e1	0.95	1.00	1.05			
L	0.25	0.35	0.50			
L1	0.10	0.20	0.30			



RECOMMENDED MINIMUM PADS FOR SC-89: 6-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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